

# SOT1547-1

LFBGA257, plastic, low profile fine-pitch ball grid array package; 257 balls; 0.8 mm pitch; 14 mm x 14 mm x 1.35 mm body

9 January 2019

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	LFBGA257
<b>Package style descriptive code</b>	LFBGA (low profile fine-pitch ball grid array)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-275A -JJAC-1
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	05-01-2016
<b>Manufacturer package code</b>	98ASA00081D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	14	-	mm
package width	-	14	-	mm
package height	-	1.35	-	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	257	-	



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2 Package outline

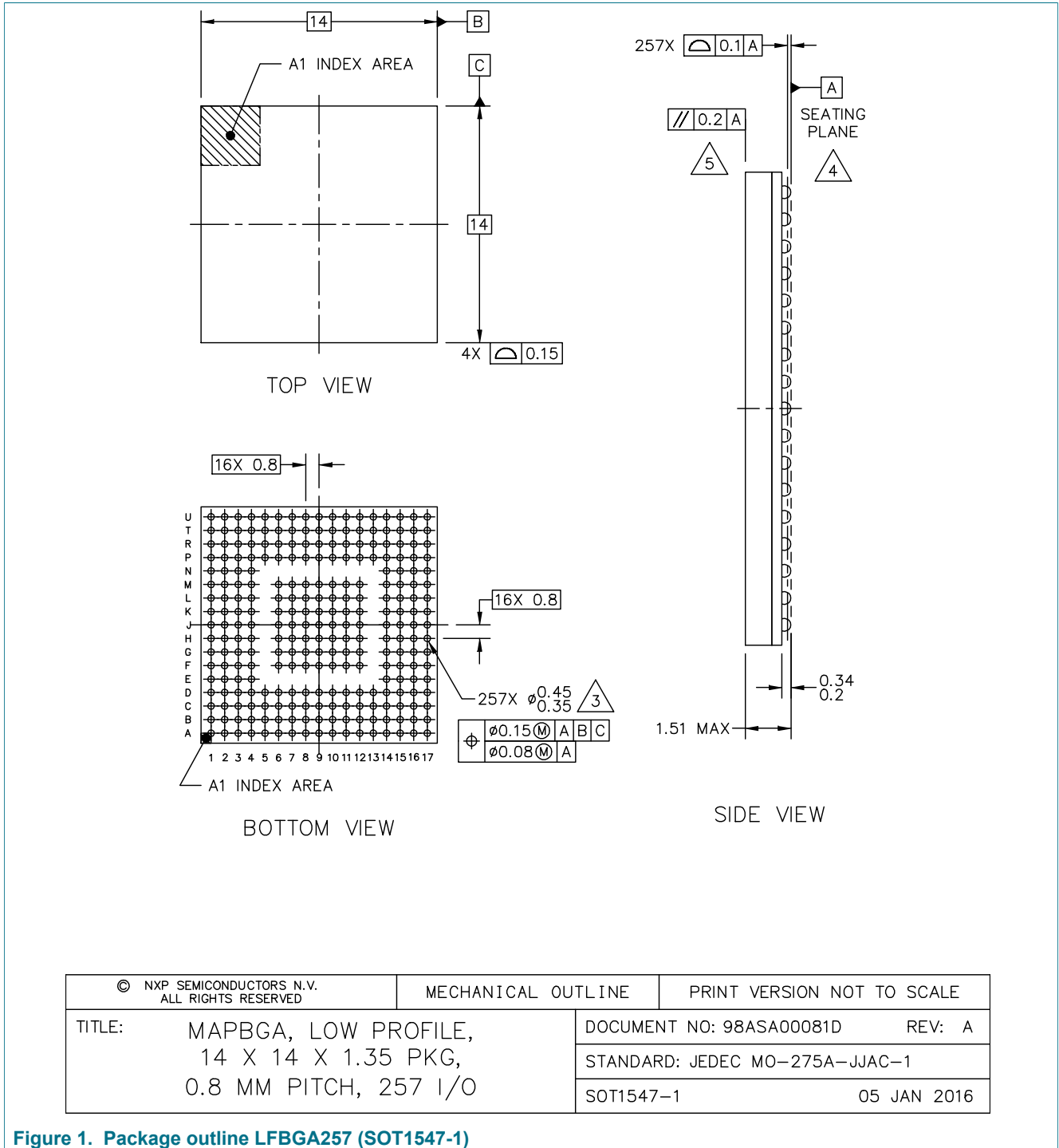


Figure 1. Package outline LFBGA257 (SOT1547-1)

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NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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TITLE: MAPBGA, LOW PROFILE, 14 X 14 X 1.35 PKG, 0.8 MM PITCH, 257 I/O	DOCUMENT NO: 98ASA00081D	REV: A
	STANDARD: JEDEC MO-275A-JJAC-1	
	SOT1547-1	05 JAN 2016

Figure 2. Package outline note LFBGA257 (SOT1547-1)

### 3 Legal information

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